Application and Efficiency: Bridge between Industry and Academia

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In the first part of this talk, I will present some of my experiences while working on various projects at Intel. Specifically, I will talk about the challenges that I encountered as well as responsibilities that need to be shouldered during the journey. Furthermore, I will discuss on the skillsets that are essential to tackle the problems and valuable lessons learnt during the whole process. In the second part, I will talk about fundamental differences between industry and academia in general and my perspective on bridging the gap between the two fields. I will share my thoughts on realizing the potential opportunity for graduate students at Department of Chemical engineering at Texas Tech to enhance their footprint in the industry. Strong work ethics, problem solving abilities, emphasis on application and efficiency via minimizing the losses and finally, effective communication skill, are central to turn this dream into reality.

Bio sketch:

Dr. Godbole received his baccalaureate and doctorate in Chemical engineering from Institute of Chemical Technology and Texas Tech University, respectively. Immediately after his Ph.D. in 2016 he joined Intel Corporation as Process TD engineer in Intel's manufacturing fab at Portland. Initially, as module engineer Dr. Godbole was responsible for designing and conducting experiments to condition the new tools per Intel standards so that the new tool could pass the set of tests and be ready to run the production material. Furthermore, He helped in improving safety, quality, yield, process capability over variables such as materials, methods etc. via utilizing his expertise in material synthesis and characterization. Currently, Dr. Godbole works as a Process Engineer in the FSM Group and partners with Intel suppliers as well as various other groups within Intel to implement 'Rest of World' equipment solutions. He is bringing new ideas to fab productivity and innovated systems, team structures and indicators that delivered new capabilities for equipment productivity team. Dr. Godbole contributes to drive cross MSO (Manufacturing Supply Chain and Operations) strategy for Intel foundry tool selection and maximize node fungibility utilizing his proficiency in plasma etching and data analysis. To date, he has received numerous divisional awards at Intel including Technology and Manufacturing Group's (TMG) excellence award, which is TMG's highest internal honor.